

PF-709AD FLIP CHIP / BALL ATTACH FLUX

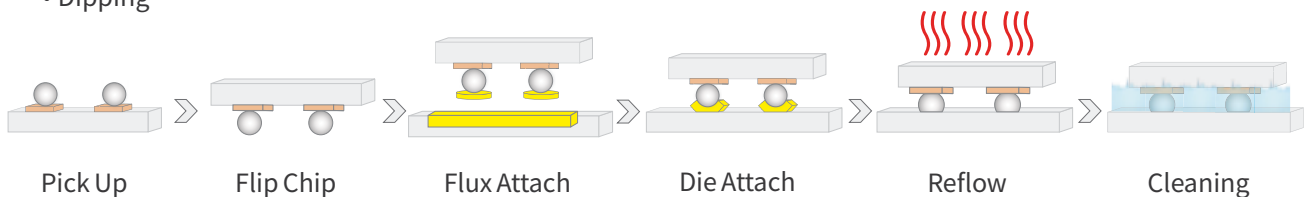
PF-709AD Halogen-Free, Water-Soluble formulation is a mixture of organic acids, thixotropic thickeners and surfactants which aid removal of post soldering residues. The fluxing activity of the flux is comparable to halogen/halide containing fluxes. This flux has been designed for dipping/pin transfer applications to deliver an optimum amount of paste flux onto the substrate. The high tackiness property provides excellent attachment of solder spheres onto BGA or CSP components. Paste flux is virtually free of air entrapment, resulting in consistent paste flux deposition.

Main Features

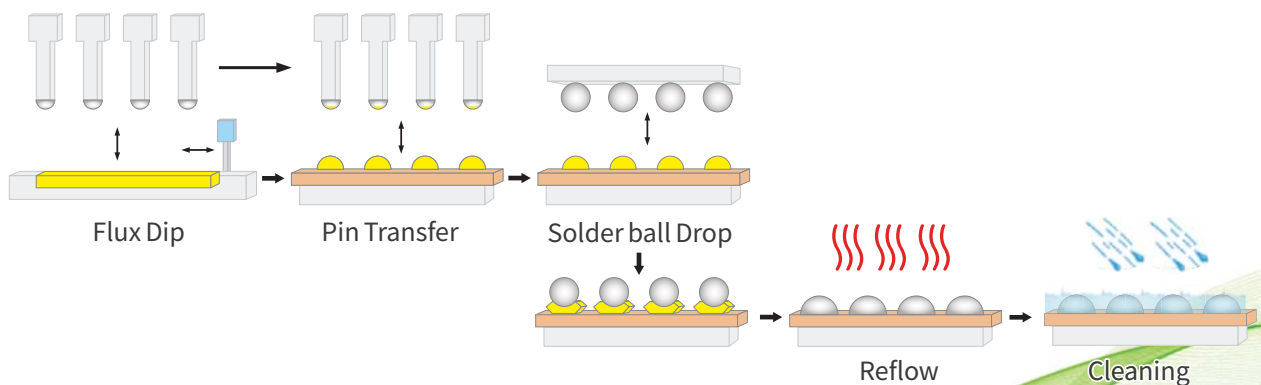


Application

• Dipping



• Pin Transfer

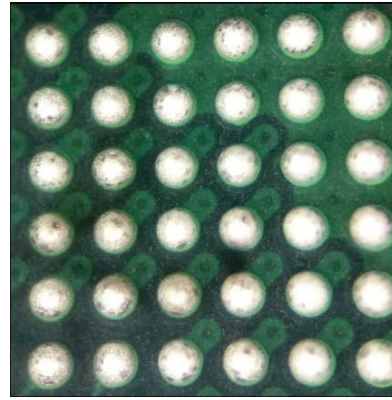


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Consistent Flux Deposition



No Ball Defect After Reflow



Typical Analysis

PROPERTIES	SPECIFICATIONS	METHOD
Flux Classification	ORH0	IPC-J-STD-004B
Appearance	Amber	Visual
pH - 5% Aqueous Solution	2.5 - 4.5	QIT
Halide Content	Halide - Free	IPC-TM-650 2.3.33 (Silver Chromate Test)
Halogen Content	Halogen - Free	EN 14582
Malcom Viscosity (@10rpm)	10 - 30 Pa.s	IPC-TM-650 2.4.34.3 (Modified)
Tack Strength	100 - 200 gf	JIS Z 3284
Surface Insulation Resistance (Cleaned)	> 1.0 x 10 ⁹ ohms	IPC-TM-650 2.6.3.3



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